## **DESCRIPTION**

The AM4407 is the P-Channel logic enhancement mode power field effect transistor is produced using high cell density. Advanced trench technology to provide excellent R<sub>DS(ON)</sub>.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application, and low in-line power loss are needed in a very small outline surface mount package.

The AM4407 is available in SOP8 Package

# ORDERING INFORMATION

Package Type	Part Number		
0000	MO	AM4407M8R	
SOP8	M8	AM4407M8VR	
Note	R: Tape & Reel		
Note	V: Green	Package	
AiT provides all Pb free products			
Suffix "V" means Green Package			

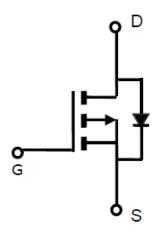
### **FEATURES**

- 30V/-12.0A,  $R_{DS(ON)} = 12m\Omega(typ)@V_{GS} = -10V$
- -30V/-7.5A,  $R_{DS(ON)} = 19m\Omega(typ)@V_{GS} = -4.5V$
- Super high density cell design for extremely low RDS(ON)
- Exceptional on-resistance and maximum DC current capability
- Available in SOP8 Package

# **APPLICATION**

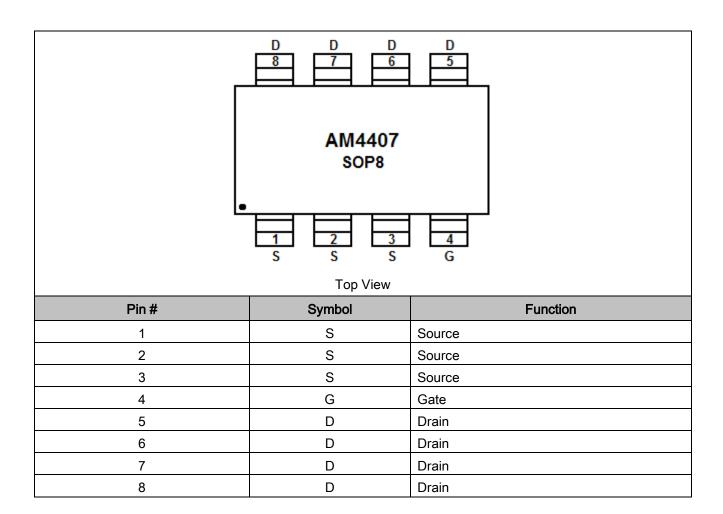
- High Frequency Point-of-Load Synchronous
- New working DC-DC Power System
- Load Switch

## P CHANNEL MOSFET



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# PIN DESCRIPTION



# THERMAL INFORMATION

Parameter	Symbol	Max	Unit
Thermal Resistance-Junction to Ambient	R <sub>0</sub> JA	85	°C/W
Thermal Resistance-Junction to Case	Rejc	28	°C/W

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# **ABSOLUTE MAXIMUM RATINGS**

#### T<sub>A</sub> = 25°C Unless otherwise specified

V <sub>DSS</sub> , Drain-Source Voltage		30V
V <sub>GSS</sub> , Gate-Source Voltage		±20V
I <sub>D</sub> , Continuous Drain Current, V <sub>GS</sub> =10V <sup>NOTE1</sup>	T <sub>A</sub> =25°C	12A
I <sub>DM</sub> , Pulsed Drain Current <sup>NOTE2</sup>		30A
P <sub>D</sub> , Power Dissipation	T <sub>A</sub> =25°C	3.2W
	T <sub>A</sub> =70°C	2W
T <sub>J</sub> , Operation Junction Temperature		-55/150°C
T <sub>STG</sub> , Storage Temperature Range		-55/150°C

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

NOTE1: The value of  $R_{\theta JA}$  is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_{A}=25^{\circ}C$ .

NOTE2: The data tested by pulsed , pulse width≦300us , duty cycle≦2%

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# **ELECTRICAL CHARACTERISTICS**

 $T_J$  = 25°C Unless otherwise specified

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Static Parameters			•			
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-30	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.0	-	-2.5	V
Gate Leakage Current	Igss	V <sub>DS</sub> =0V,V <sub>GS</sub> =±20V	-	-	±100	nA
Zero Gate Voltage Drain		V <sub>DS</sub> =-24V,V <sub>GS</sub> =0V	-	-	-1	
Current	I <sub>DSS</sub>	V <sub>DS</sub> =-24V,V <sub>GS</sub> =0V T <sub>J</sub> =55°C	-	-	-5	μΑ
Drain-source On-Resistance	Б	V <sub>GS</sub> =-10V,I <sub>D</sub> =-12A	-	12	15	~~ (
	R <sub>DS(ON)</sub>	Vgs=-4.5V, ID=-7.5A	-	19	25	mΩ
Forward Transconductance	G <sub>fs</sub>	V <sub>DS</sub> =-5V,I <sub>D</sub> =-30.0A	-	24	-	S
Source-Drain Diode						
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-2.3A,V <sub>GS</sub> =0V	-	-0.75	-1.0	V
Dynamic Parameters						
Total Gate Charge	Qg	V <sub>DS</sub> =-15V	-	21	-	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> =4.5V	-	5.2	-	nC
Gate-Drain Charge	$Q_{gd}$	I <sub>D</sub> =-12A	-	7.5	-	
Input Capacitance	Ciss	\\ - 45\\	-	2220	-	
Output Capacitance	Coss	V <sub>DS</sub> =-15V	-	320	-	
Reverse Transfer Capacitance	Crss	V <sub>GS</sub> =0V f=1MHz	-	235	-	pF
Turn-On Time	t <sub>d(on)</sub>		-	34	-	
	tr	- V <sub>DD</sub> =15V	-	35	-	
Turn-Off Time	t <sub>d(off)</sub>	V <sub>GS</sub> =-10V	-	70	-	nS
	t <sub>f</sub>	$I_D$ =-5A, $R_G$ =3.3 $\Omega$	-	12	-	

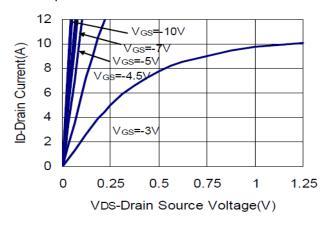
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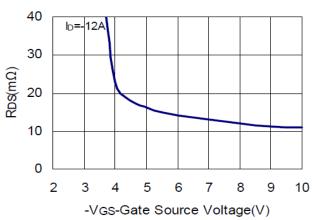
# TYPICAL CHARACTERISTICS

### T<sub>A</sub>=25°C Unless specified

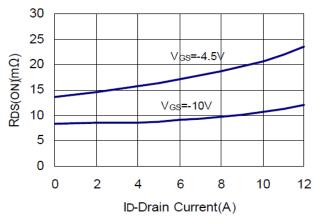
#### 1. Output Characteristics



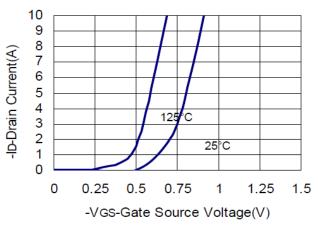
#### 2. Drain-Source On Resistance



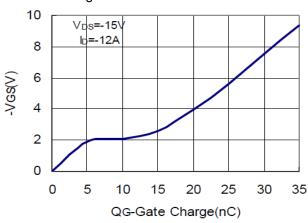
#### 3. Drain Source On Resistance



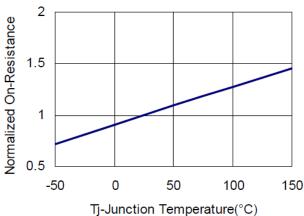
4. Transfer Characteristics



#### 5. Gate Charge



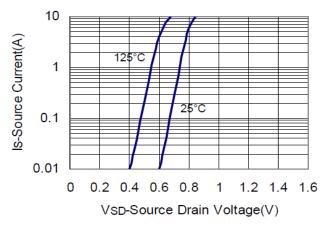
6. Drain Source Resistance



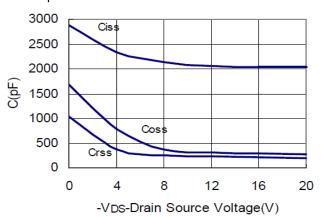
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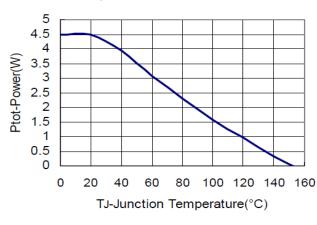




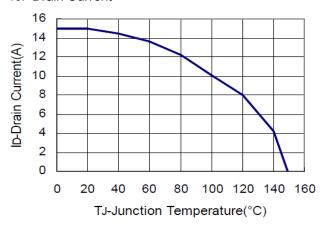
#### 8. Capacitance



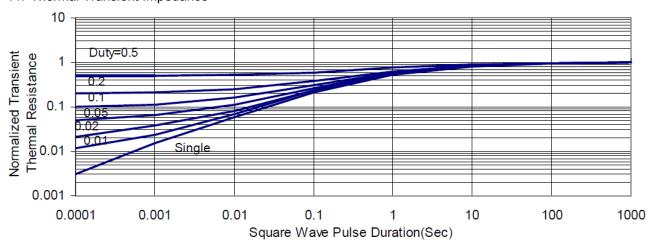
#### 9. Power Dissipation



#### 10. Drain Current



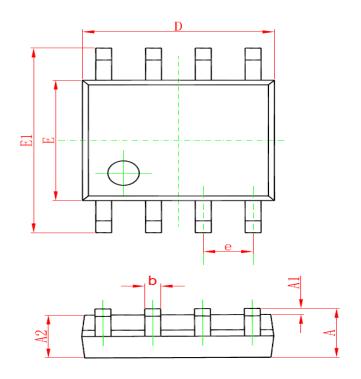
### 11. Thermal Transient Impedance

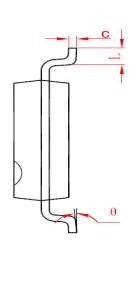


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# PACKAGE INFORMATION

Dimension in SOP8 (Unit: mm)





Symbol	Min	Max		
Α	1.350	1.750		
A1	0.100	0.250		
A2	1.350	1.550		
b	0.330	0.510		
С	0.170	0.250		
D	4.700	5.100		
E	3.800	4.000		
E1	5.800	6.200		
е	1.270(BSC)			
L	0.400	1.270		
θ	0°	8°		

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